

INTERNATIONAL CENTRE FOR APPLIED SCIENCES
 (Manipal University)
IV SEMESTER B.S. DEGREE EXAMINATION - MAY 2016
SUBJECT: VLSI DESIGN (EC 245)
 (BRANCH: E & C)
23RD MAY, 2016

Time: 3 Hours

Max. Marks: 100

- ✓ **Answer ANY FIVE full Questions.**
- ✓ **Layout must be drawn using the graph sheet provided.**
- ✓ **Missing data may be suitably assumed.**

- 1A. Explain the operation of pseudo NMOS inverter. Derive Z_{pu}/Z_{pd} ratio for pseudo NMOS inverter driven from a similar inverter.
- 1B. Explain in detail about working of MOS capacitor.
- 1C. What do you understand by channel length modulation? Explain in detail. (10+5+5)
- 2A. With the help of neat circuit diagram and curve, explain the working of CMOS inverter. Derive the expression for V_{inv} . Discuss the merits of CMOS inverter over NMOS inverter with depletion load.
- 2B. Calculate the effective capacitance for the given multi-layer structure in **Figure 2B** for $5\mu\text{m}$ process. Relative Capacitance value for metal1= 0.075, polysilicon=0.1 and Gate to channel = 1.0. (10+10)
- 3A. Explain the principle of photo lithography. Discuss the working of positive photo resist and negative photo resist with necessary diagrams.
- 3B. For a CMOS Inverter having $L_n = L_p = W_n = 2\mu\text{m}$, $W_p = 5\mu\text{m}$. Compute the following: (i) rise time t_r , (ii) fall-time t_f (iii) total delay T_d through a pair of inverters. Given the typical sheet resistance and standard capacitance values for $2\mu\text{m}$ process:
 [i] NMOS channel resistance = $20\text{ k}\Omega/\text{square}$ [ii] PMOS channel resistance = $45\text{ k}\Omega/\text{square}$ [iii] Gate-to-channel capacitance = $8\text{pF} \times 10^{-4}/\mu\text{m}^2$.
- 3C. With neat figures explain the different steps involved in the fabrication of NMOS transistor. What is the advantage of self-aligned process? (5+5+10)
- 4A. Draw the circuit, stick diagram and layout for two input CMOS EXNOR gate.
- 4B. Implement 2 input NAND and NOR functions using following approach:
 [a] pass transistors, [b] Transmission gates, [c] NMOS logic with depletion load, [d] CMOS logic (10+10)
- 5A. Give the circuit implementation of following multiple output function using NMOS based PLA. Give the stick notation. $Z_1 = AB + \bar{A}\bar{B}C$; $Z_2 = AB$; $Z_3 = A + \bar{B}C$.
- 5B. Give hardware implementation for storing following 4-bit words using NMOS ROM structure. word1: 0101; word2: 0010; word3: 1001; word4: 0110
- 5C. Calculate I_D and V_{SD} , and indicate region of operation of transistor M1 for the circuit in **Figure 5C**. $V_{tp} = -0.4\text{ V}$, $K_p = 120\mu\text{A}/\text{V}^2$, and $W/L = 2$. (5+5+10)

- 6A. Discuss the structured design implementation of $(n+1)$ -bit parity indicator block that is provided with $n + 1$ bit input word $A_n A_{n-1} A_{n-2} \dots A_1 A_0$. The circuit has one bit parity output P. P will be HIGH (LOW) for even (odd) number of 1s at input. Give the stick notation for CMOS implementation of standard cell.
- 6B. i) With the help of a neat circuit diagram, explain the operation of BiCMOS inverter. Also highlight the role of each transistor in the circuit.
 ii) What are the merits and demerits of the BiCMOS logic. (10+10)
- 7A. Compare and contrast CMOS, bipolar and GaAs technologies.
- 7B. Discuss cascaded inverters as drivers for driving large capacitive loads and derive the necessary expressions. (10+10)
- 8A. Explain the fabrication process of DMESFET using planar technology with necessary diagrams.
- 8B. Explain different scaling models. Discuss the effect of different scaling on following parameters: [i] Gate oxide capacitance C_g [ii] Channel resistance R_{on} [iii] Gate delay T_d (10+10)

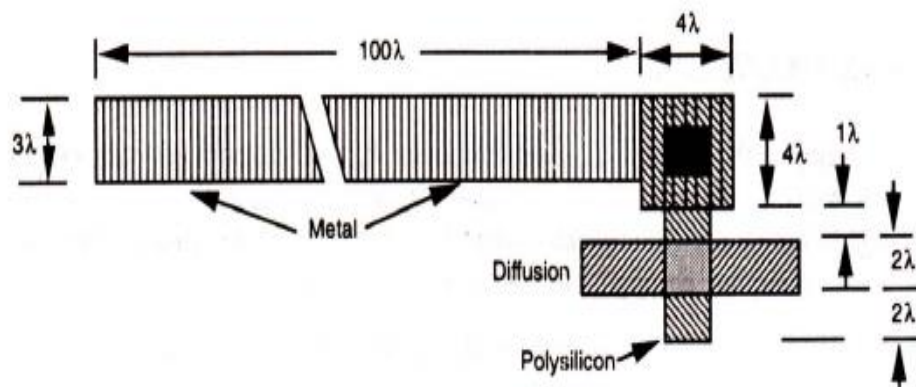


Figure 2B

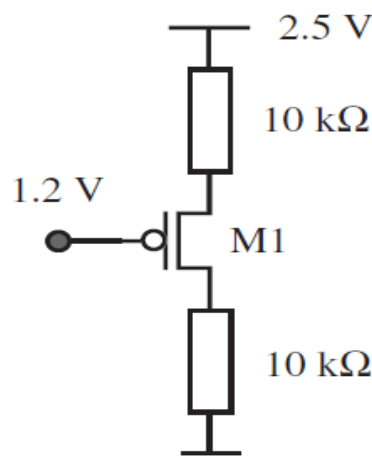


Figure 5C

